

LNPTM THERMOCOMPTM COMPOUND DX13354

DESCRIPTION

LNP THERMOCOMP DX13354 compound is based on Polycarbonate (PC) resin containing 30% glass fiber. Added features of this grade include: Improved Plating Surface and Mechanical Performance targeted for Laser Direct Structuring (LDS) applications, Improved Impact, Good Surface Aesthetics and Wide Processing Window.

GENERAL INFORMATION	
Features	Dielectrics, Laser Direct Structuring, Aesthetics/Visual effects, Impact resistant, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Automotive	Automotive Interiors
Consumer	Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

PROPERTIES TYPICAL VALUES UNITS **TEST METHODS** MECHANICAL⁽¹⁾ Tensile Stress, brk, Type I, 5 mm/min 120 MPa ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 2.4 % ASTM D638 Tensile Modulus, 5 mm/min 8760 MPa ASTM D638 Flexural Stress 170 MPa ASTM D790 ASTM D790 8020 Flexural Modulus MPa Tensile Stress, break, 50 mm/min 120 MPa ISO 527 Tensile Strain, break, 50 mm/min % ISO 527 2.4 Tensile Modulus, 1 mm/min 8840 MPa ISO 527 Flexural Stress 180 ISO 178 MPa Flexural Modulus 8450 MPa ISO 178 IMPACT (1) Charpy Impact, unnotched, 23°C 50 kJ/m² ISO 179/2C 700 ASTM D4812 Izod Impact, unnotched, 23°C J/m Izod Impact, notched, 23°C 150 J/m ASTM D256 Izod Impact, unnotched 80*10*4 +23°C 40 kJ/m² ISO 180/1U Izod Impact, notched 80*10*4 +23°C 14 ISO 180/1A kJ/m² ISO 179/2C Charpy Impact, notched, 23°C 14 kJ/m² THERMAL (1) HDT, 0.45 MPa, 3.2 mm 126 °C ASTM D648 °C ASTM D648 HDT, 1.82 MPa, 3.2 mm 122

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CHEMISTRY THAT MATTERS

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, flow	2.1E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	6.9E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	2.1E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	7.1E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	127	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	124	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.47		ASTM D792
Mold Shrinkage, flow, 3.2 mm ⁽²⁾	0.05 – 0.1	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm ⁽²⁾	0.2 - 0.4	%	SABIC method
Melt Flow Rate, 280°C/2.16 kgf	10	g/10 min	ASTM D1238
Melt Flow Rate, 280°C/5.0 kgf	27	g/10 min	ASTM D1238
Melt Flow Rate, 300°C/1.2 kgf	16	g/10 min	ASTM D1238
Melt Volume Rate, MVR at 300°C/1.2 kg	13	cm³/10 min	ASTM D1238
ELECTRICAL ⁽¹⁾			
Dielectric Constant, 1.1 GHz	3.52		SABIC method
Dielectric Constant, 1.9 GHz	3.44	-	SABIC method
Dielectric Constant, 5 GHz	3.51	-	SABIC method
Dissipation Factor, 1.1 GHz	0.014	-	SABIC method
Dissipation Factor, 1.9 GHz	0.013	-	SABIC method
Dissipation Factor, 5 GHz	0.012	-	SABIC method
INJECTION MOLDING ⁽³⁾			
Drying Temperature	110	°C	
Drying Time	3 – 4	Hrs	
Melt Temperature	270 – 295	°C	
Nozzle Temperature	270 – 295	°C	
Front - Zone 3 Temperature	270 – 295	°C	
Middle - Zone 2 Temperature	270 – 295	°C	
Rear - Zone 1 Temperature	270 – 295	°C	
Mold Temperature	100 – 120	°C	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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